



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2018-07-04
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD Champion
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		


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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
Legal Statement	Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.		

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STGW60H65DFB	TDLW*EWF7R52	A	3068	2018-07-04
	Amount	UoM	Unit type	ST ECOPACK Grade
	4430.00	mg	Each	ECOPACK2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
NA	NA	NA		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	15.75-20.15-5.15	3	Through-hole	
Comment	TO 247			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 25th May 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	1.09	Die - Leadframe	246
Lead	17.07	Soft solder	3854

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name		TDLW*EWF7R52				
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Dies	M-011 Other inorganic materials	14.017	mg	supplier	die	Silicon (Si)	7440-21-3		13.205	mg	942108	2981
				supplier	metallization	Aluminium (Al)	7429-90-5		0.264	mg	18834	60
				supplier	Passivation	Silicon Nitride	12033-89-5		0.035	mg	2497	8
				supplier	Passivation	Silicon Oxide	7631-86-9		0.115	mg	8204	26
				supplier	back side metallization	Aluminium (Al)	7429-90-5		0.054	mg	3852	12
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.017	mg	1213	4
				supplier	back side metallization	Gold (Au)	7440-57-5		0.012	mg	856	3
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.174	mg	12413	39
				supplier	back side metallization	Vanadium (V)	7440-62-2		0.009	mg	642	2
				supplier	back side metallization	Silver (Ag)	7440-22-4		0.039	mg	2782	9
Leadframe	M-004 Copper and its alloys	2826.183	mg	supplier	polymer die coating	Probimide	Proprietary		0.093	mg	6599	21
				supplier	alloy	Copper (Cu)	7440-50-8		2821.521	mg	998350	636912
				supplier	alloy	Iron (Fe)	7439-89-6		2.825	mg	1000	635
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.848	mg	300	191
				supplier	metallization	Nickel (Ni)	7440-02-0		0.915	mg	324	207
Soft solder	Solder	17.877	mg	JIG - R	solder	Lead (Pb)	7439-92-1	7a-Lead in high me	17.072	mg	954970	3854
				supplier	solder	Silver (Ag)	7440-22-4		0.447	mg	25004	101
				supplier	solder	Tin (Sn)	7440-31-5		0.358	mg	20026	81
				supplier	wire	Aluminium (Al)	7429-90-5		1.762	mg	996043	398
Bonding wires	M-011 Other inorganic materials	1.769	mg	supplier	wire	Magnesium (Mg)	7439-95-4		0.007	mg	3957	2
				supplier	mold compound	Silica, vitreous	60676-86-0		1357.946	mg	870000	306534
				supplier	mold compound	Epoxy resin	25068-38-6		156.086	mg	100000	35234
Encapsulation	M-011 Other inorganic materials	1560.858	mg	supplier	mold compound	Phenol resin	29690-82-2		39.022	mg	25000	8809
				supplier	mold compound	Carbon Black	1333-86-4		7.804	mg	5000	1762
				supplier	solder alloy	Tin (Sn)	7440-31-5		9.296	mg	1000000	2098